



EXV

What Is Our Project About?

The project serves as a validation suite for the mainboard being designed using a RISC-V processor laptop designed for deep-space missions. Leveraging NASA and Microchip's High-Performance Spaceflight Computing (HPSC) processor, this project demonstrates the feasibility of a resilient, energy-efficient laptop capable of withstanding space radiation.

Radiation Threats to Hardware

- Single Event Effects (SEE) can disrupt electronic components when high-energy particles strike a device. These effects can cause bit shifts, altering the state of a circuit (e.g., changing a '0' to a '1'), which may lead to software errors or system crashes.
- Total lonizing Dose (TID): Causes undesirable charge collection at silicon and insulator interfaces, leading to performance issues and potential failure over time.TID can permanently damage components as the degradation accumulates.
- Displacement Damage Dose (DDD): Displaces atoms in silicon/dopant lattice structures, creating defects that impair device performance. DDD can also lead to permanent damage in affected components.

Design Objective

- Project Goal: Create a validation suite for the Polarfire Icicle Kit that can be translated to the Biz Board when the board is ready for testing.
- Reference Design: We are using Baremetal examples to test the functionality of all components that need to be tested. We have decided to use the Icicle Kit as a reference due to its similarity to the redesigned Biz Board. Some of these baremetal examples include.
- DDR baremetal example
- UART baremetal example
- SPI slave master baremetal example
- USB HID baremetal example
- Expected Outcome: A validation suite suitable for future design toward a HPSC based radiation tolerant mainboard.



Fig. 1: Design Objectives



RADIATION-TOLERANT CREW LAPTOP

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Laptop Mainboard Implementation









We used the Icicle Development board to create a validation suite demonstrating functionality of all components that will need testing on the redesigned Biz Board. By testing the functionality of each component we will ensure they will work in a RISC-V ISA ecosystem. Our validation suite serve as a foundation for all code associated with testing and debugging for the final radiation-tolerant crew laptop.



Fig. 5: Icicle Kit Development Board (Courtesy of Microchip)



Fig. 6: HPSC Processor (Courtesy of Microchip)

Fig. 4: Device Tree Example

- the Icicle Kit.
- of each subsection.





A Platform for Continuous Innovation:

The Radiation-Tolerant Crew Laptop project provides a path toward a HPSC processor based crew laptop suitable for deep space missions. Our project will work as a proof of concept, so future teams can build off our design and work toward an HPSC based laptop.

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Accomplishments

• Successfully booted Linux on Icicle kit allowing us to navigate through and edit the device tree and file system of the board.

• Successfully used SoftConsole to edit and run all code associated with

• Found and edited baremetal code examples to validate the components

• Found and edited the HSS boot loader code for the Icicle kit allowing for a more detailed boot helping detect any errors during the boot process.

• Successfully found a method of switching between boot modes allowing the board to boot as expected for each modes use.

Fig. 7: Libero FPGA Design

Path Forward

Next Steps and Development Goals:

• Verify functionality of all baremetal examples and ensure that they allow for full validation of each component needed to be tested.

• Integrate all baremetal examples needed for the Biz Board in order to accommodate for any changes made from Icicle to Biz Board

• Optimizing firmware and software to improve functionality and efficiency



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